

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Multiple sheets used when necessary)

SHEET 1 OF 3

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| Application No. | 10/826,219 |
| Filing Date | April 16, 2004 |
| First Named Inventor | Homayoun Talieh |
| Art Unit | 1742 |
| Examiner | Unknown |
| Attorney Docket No. | ASMNUT.037C5 |

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| Examiner Initials | Cite No. | Document Number | Publication Date | Name of Patentee or Applicant | Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear |
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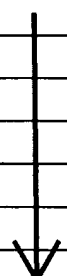
Examiner Signature /Lois Zheng/

Date Considered 03/19/2007

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

T¹ - Place a check mark in this area when an English language Translation is attached.

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| In re application of: Talieh et al. Serial No.: 10/459,321 Filed: June 10, 2002 Title: Device Providing Electrical Contact To The Surface Of A Semiconductor Workpiece During Processing | Group Art Unit: Not yet assigned Examiner: Not yet assigned Docket: NT-105C5-US |
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